

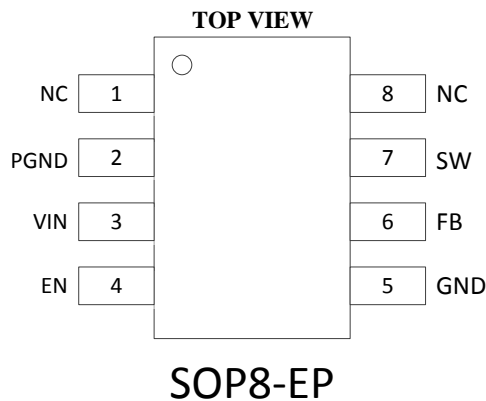
### ■ General Description

The MST9225 is a high efficiency current-mode boost converter with a fixed operation frequency. The MST9225 integrates a very low Rds-on NMOSFET to reduce power loss and achieve high efficiency. The maximum efficiency is up to 93%. The peak current of power MOSFET is limited to 5.5A. 1.2MHz operation frequency minimizes L and C value, and internal compensation network reduces external component counts. SOP8-EP package provides the best solution for PCB heat dissipation.

### ■ Features

- Wide Input Range: 2.5V to 6V
- Maximum Output: 8V
- Up to 2.5A output Current with 3.0V to 4.5V Input
- 1.2MHz switching Frequency
- Low RDS (ON): 70mΩ
- Up to 93% Efficiency
- Under-Voltage Lockout Protection
- Over-Temperature Protection
- Internal Soft Start
- Less Than 1uA Shutdown Current
- Accurate Reference: 0.6V Voltage Reference

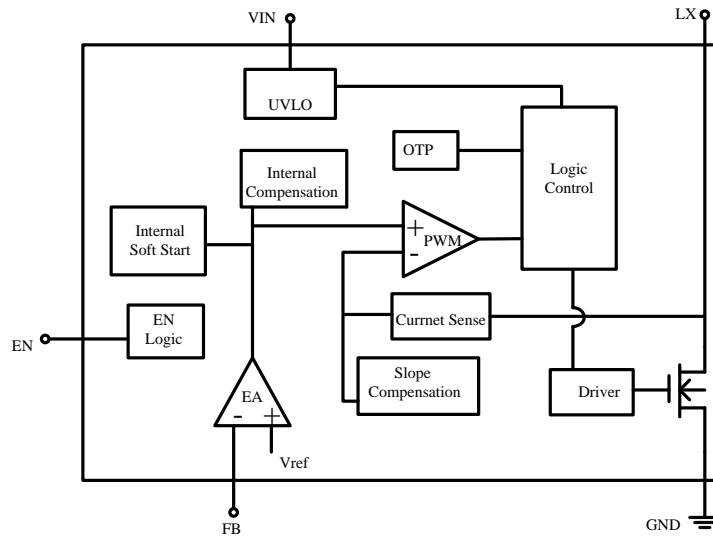
### ■ Pin Configuration



### ■ Pin Descriptions

Pin Name		Pin Function
1	NC	No Internal Connection
2	PGND	Power Ground
3	VIN	Input Supply. Must be locally bypassed.
4	EN	Enable. A high input at EN enables the device and a low input disables the devices. When not used, connect EN to the input source for automatic startup.
5	GND	Ground
6	FB	Feedback
7	SW	Power Switch Output. Connect the inductor and the blocking Schottky diode to SW.
8	NC	No Internal Connection

■ **Function Block Diagram**



■ **Absolute Maximum Ratings**

SYMBOL	NAME	VALUE	UNIT
$V_{IN}$	Input Voltage	-0.3~6.5	V
$V_{SW}$	Voltage at SW Pin	-0.5~12	V
$V_{IO}$	All Other I/O Pins	GND-0.3 to $V_{IN}+0.3$	V
$P_{TR1}$	Thermal Resistance(ESOP8) $\Theta_{JA}$	50	$^{\circ}C/W$
$T_{stg}$	Storage Temperature	-55 to 150	$^{\circ}C$
$T_{solder}$	Package Lead Soldering Temperature	260 $^{\circ}C$ , 10s	
ESD Susceptibility	HBM(Human Body Mode)	2	kV

Note1: Exceeding these ratings may damage the device.

■ **Recommended Operating Conditions(Note 2)**

SYMBOL	NAME	VALUE	UNIT
$V_{IN}$	Supply Voltage	2.5 to 6	V
$V_{out}$	Output Voltage	$V_{IN}$ to 8	V
$T_{OTP}$	Operating Temperature	-40 to +85	$^{\circ}C$

Note2: The device is not guaranteed to function outside of its operating rating.

■ **Electrical Characteristics**

(VIN = 3.3V, VOUT=5V, IOUT=100mA, TA = 25°C unless otherwise specified)

SYMBOL	ITEMS	CONDITIONS	Min.	Typ.	Max.	UNIT
V <sub>IN</sub>	Input Voltage		2.5		6	V
<b>Feedback</b>						
V <sub>FB</sub>	Feedback Voltage		588	600	612	mV
I <sub>bias</sub>	FB Pin Input Bias Current			0.05	1	μA
<b>UVLO</b>						
UVLO	Under Voltage Lockout			2.1		V
<b>Operating Current</b>						
I <sub>off</sub>	Operating Current (Shutdown)			0.1	1	μA
I <sub>sby</sub>	No Switching	V <sub>in</sub> =3V V <sub>FB</sub> =0.7V		100		μA
F <sub>sw</sub>	Switching Frequency			1.2		MHz
D <sub>max</sub>	Maximum Duty Cycle	V <sub>FB</sub> =0V		90		%
<b>Chip Enable</b>						
V <sub>EN_H</sub>	EN Minimum High Level		1.5			V
V <sub>EN_L</sub>	EN Maximum Low Level				0.4	V
V <sub>HYS</sub>	EN Hysteresis			90		mV
I <sub>EN</sub>	EN Input Bias Current				1	μA
<b>OTP</b>						
OTP	Thermal Shutdown Temperature			130		°C
OTP Hystersis				20		°C
<b>Output Switch</b>						
R <sub>ON</sub>	SW On Resistance (Note 3)			70		mΩ
I <sub>LIMIT</sub>	SW Current Limit			5.5		A
I <sub>LEAK</sub>	SW Leakage Current	V <sub>sw</sub> =5V		0.01	1	μA
<b>Open Circuit Protection</b>						
V <sub>OVP</sub>	Over Voltage Protection	V <sub>OVP</sub> Rising		10		V
<b>Soft Start</b>						
t <sub>ss</sub>	Soft Start Time (Note 3)	V <sub>IN</sub> Power On		400		μS

Note3: Guaranteed by design.

■ Typical Performance Characteristics

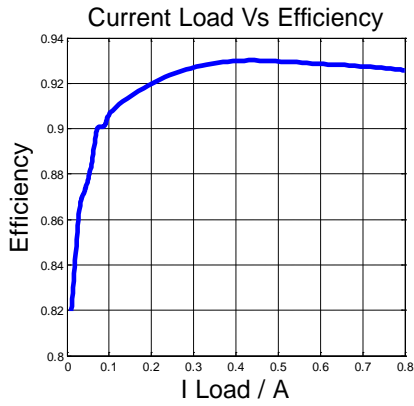


Fig 1 Efficiency Vs Light Load

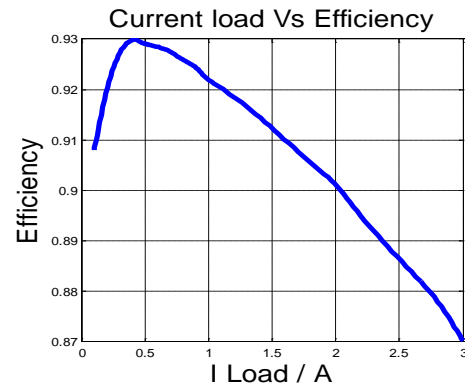


Fig 2 Efficiency Vs Heavy Load

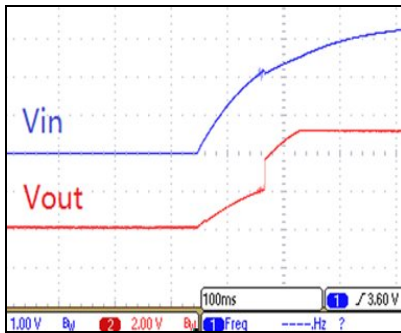


Fig 3 Startup with  $V_{IN}$

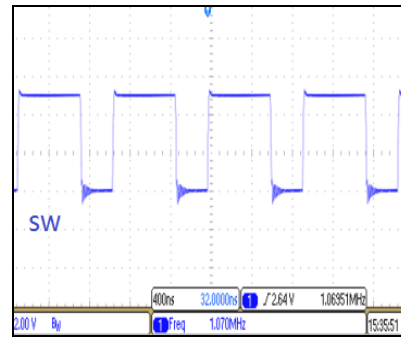


Fig 4 SW Waveform

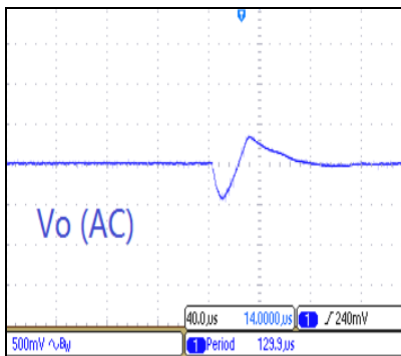


Fig 5 Transient Response  
( $V_{IN}=3.6V$ ,  $V_{out}=5V$ ,  $I_{load}=0.15A$  to  $0.9A$ )

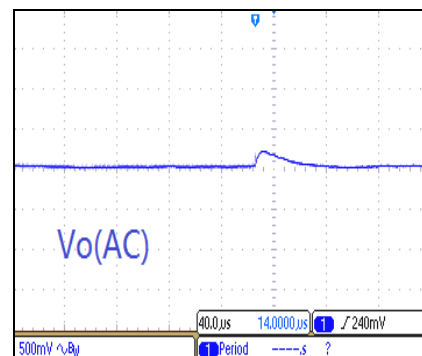


Fig 6 Transient Response  
( $V_{IN}=3.6V$ ,  $V_{out}=5V$ ,  $I_{load}=0.9A$  to  $0.15A$ )

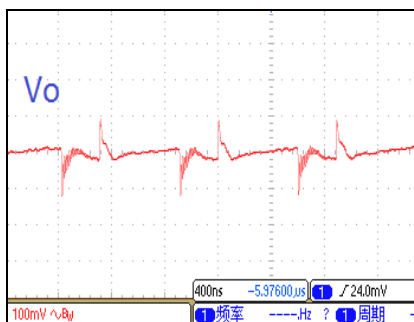


Fig 7 Vout Ripple

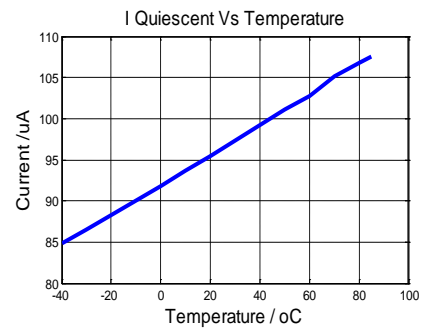
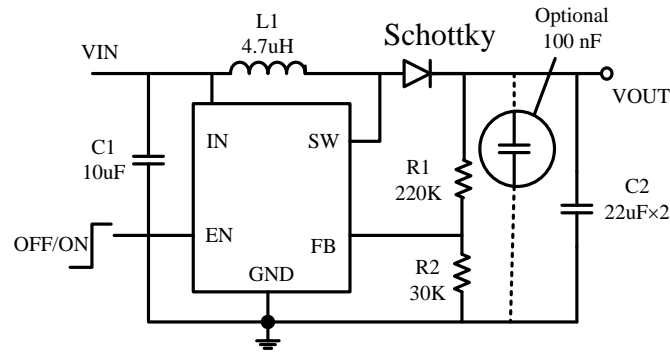


Fig 8 Quiescent Current Vs Temperature

■ **Typical Application Circuit**



Typical application

■ **Operation Description**

The MST9225 adopts fixed frequency, peak current mode boost regulator architecture to regulate output voltage. The operating principle of the MST9225 can be easily understood by referring to the functional block diagram. At the beginning of each oscillator cycle the MOSFET is turned on by the control circuit. To prevent sub-harmonic oscillations at duty cycle larger than 50 percent, a stabilizing ramp is added to the output of the current sense amplifier and the result is fed into the negative input of the PWM comparator. When this voltage equals the output voltage of the error amplifier, the power MOSFET is turned off. The voltage at the output of the error amplifier is an amplified result of the difference between the 0.6V reference voltage and the feedback voltage. In this way the peak current level keeps the output voltage in regulation. If the feedback voltage starts to drop, the output of the error amplifier increases, resulting in more current to flow through the power MOSFET, thus increasing the power delivered to the output. The MST9225 has internal soft start to avoid rush input current during the startup and also to avoid overshoot on the output.

■ **Application Information**

Because of the high integration in the MST9225, the application circuit based on this regulator IC is rather simple. Only input capacitor CIN, output capacitor COUT, inductor L, schottky diode and feedback resistors (R1 and R2) need to be selected for the targeted applications.

**Feedback Resistor Divider R1 and R2:**

Choose R1 and R2 to program the proper output voltage. To minimize the power consumption under light loads, it is desirable to choose large resistance values for both R1 and R2. A value of between 10KΩ and 1MΩ is recommended for both resistors. If R1=220 KΩ is chosen, then R2 can be calculated to be 30KΩ based on the following equation:

$$R2 = (R1 \times 0.6V) / (VOUT - 0.6V)$$

**Input Capacitor CIN:**

To minimize the potential noise problem, place a typical X5R or better grade ceramic capacitor really close to the IN and GND pins. Care should be taken to minimize the loop area formed by CIN, and IN/GND pins. In this case a 10uF low ESR ceramic is recommended.

**Output Capacitor COUT:**



The output capacitor is selected to meet the output ripple noise requirements. Both steady state ripple and transient requirements must be taken into consideration when selecting this capacitor. For the best performance, it is recommended to use X5R or better grade ceramic capacitor with 10V rating and more than two pieces of 22uF Capacitor. The ESR of the capacitor COUT is critical for low ripple and noise in the output voltage.

**Boost Inductor L:**

The recommended values of inductor is 2.2uH to 10 u H. Small size and better efficiency are the major concerns for portable devices. The inductor should have low core loss at 1.2MHz and low DCR for better efficiency. To avoid inductor saturation current rating should be considered.

**Diode Selection:**

Schottky diode is a good choice for MST9225 because of its low forward voltage drop and fast reverses recovery in order to get better efficiency. The high speed rectification is also a good characteristic of Schottky diode for high switching frequency. The diode reverse breakdown voltage should be larger than the output voltage.

**Start-up and Inrush Current:**

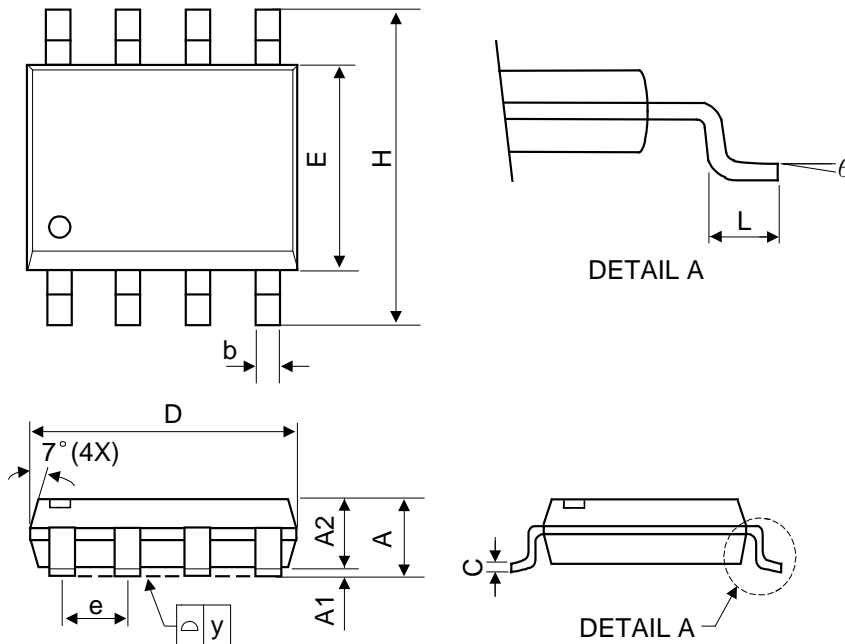
The MST9225 has internal soft start to limit the value of current through VIN during the startup and also to avoid overshoot on the output. The soft start is realized by gradually increasing the output of error amplify during start-up.

■ **Ordering Information**

Part Number	OVP(V)	Package	Marking
MST9225KP	10	SOP8-EP	MST9225 XXXX

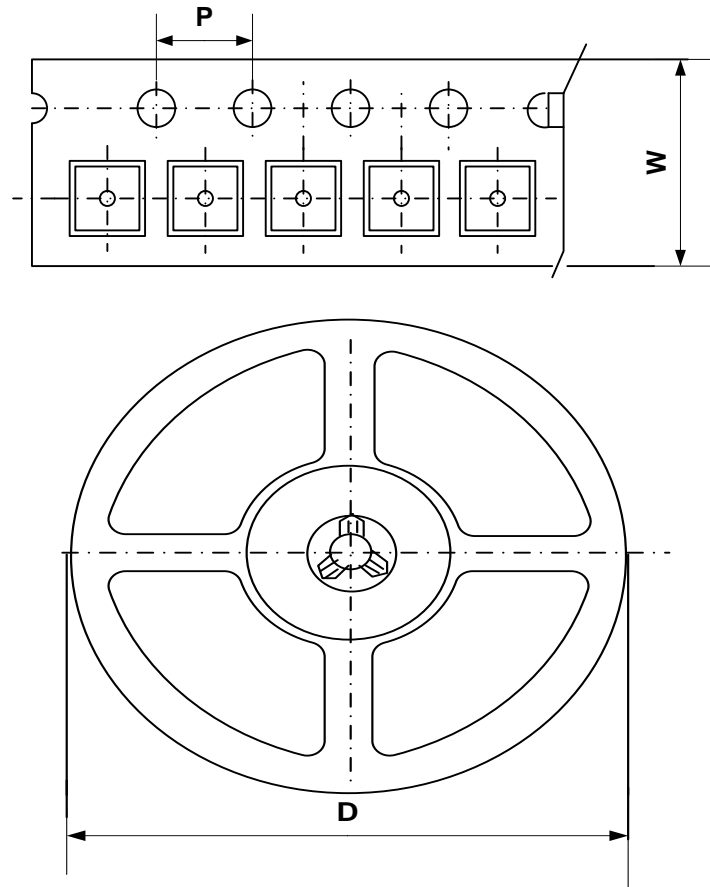
■ Package Outlines

SOP8-EP



SYMBOL	MILLIMETER			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	-	-	1.75	-	-	0.069
A1	0.1	-	0.25	0.04	-	0.1
A2	1.25	-	-	0.049	-	-
C	0.1	0.2	0.25	0.0075	0.008	0.01
D	4.7	4.9	5.1	0.185	0.193	0.2
E	3.7	3.9	4.1	0.146	0.154	0.161
H	5.8	6	6.2	0.228	0.236	0.244
L	0.4	-	1.27	0.015	-	0.05
b	0.31	0.41	0.51	0.012	0.016	0.02
e	1.27 BSC			0.050 BSC		
y	-	-	0.1	-	-	0.004
θ	0°	-	8°	0°	-	8°

■ Packing Information



Package Type	Carrier Width (W)	Pitch (P)	Reel Size(D)	Packing Minimum
SOP8-EP	8.0±0.1 mm	4.0±0.1 mm	180±1 mm	2500pcs

Note: Carrier Tape Dimension, Reel Size and Packing Minimum



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